

Title (en)
Curable organosiloxane compositions and semiconductor devices

Title (de)
Härtbare Organosiloxanzusammensetzungen und Halbleiterbauelemente

Title (fr)
Compositions durcissables d'organosiloxane et dispositifs semi-conducteur

Publication
EP 0757080 A3 19970702 (EN)

Application
EP 96305624 A 19960731

Priority
• JP 21985995 A 19950804
• JP 21986095 A 19950804

Abstract (en)
[origin: EP0757080A2] A curable organosiloxane composition useable as a silicone die attach adhesive, an electrically conductive silicone rubber composition each comprising a composition that cures through both addition and condensation reactions, that will not impair wire bondability to a semiconductor chip or lead frame after the semiconductor chip has been bonded to a substrate or package; and semiconductor devices in which the semiconductor chip is bonded to its substrate or package using the curable organosiloxane composition and in which the semiconductor device that evidences high reliability by virtue of the use of the curable organosiloxane composition.

IPC 1-7
C08L 83/04; C09J 183/04; H01L 21/50

IPC 8 full level
C08K 3/08 (2006.01); **C08L 83/04** (2006.01); **C09J 183/04** (2006.01); **H01L 21/58** (2006.01); **H01L 23/495** (2006.01)

CPC (source: EP KR US)
C08K 3/08 (2013.01 - EP US); **C08L 83/00** (2013.01 - EP US); **C08L 83/04** (2013.01 - EP KR US); **C09J 183/04** (2013.01 - EP US); **H01L 23/49513** (2013.01 - EP US); **H01L 24/29** (2013.01 - EP US); **H01L 24/32** (2013.01 - EP US); **H01L 24/83** (2013.01 - EP US); **C08G 77/12** (2013.01 - EP US); **C08G 77/18** (2013.01 - EP US); **C08G 77/20** (2013.01 - EP US); **H01L 24/45** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 24/73** (2013.01 - EP US); **H01L 2224/29** (2013.01 - EP US); **H01L 2224/29101** (2013.01 - EP US); **H01L 2224/2919** (2013.01 - EP US); **H01L 2224/29191** (2013.01 - EP US); **H01L 2224/29298** (2013.01 - EP US); **H01L 2224/32225** (2013.01 - EP US); **H01L 2224/32245** (2013.01 - EP US); **H01L 2224/45124** (2013.01 - EP US); **H01L 2224/45144** (2013.01 - EP US); **H01L 2224/45147** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48227** (2013.01 - EP US); **H01L 2224/48247** (2013.01 - EP US); **H01L 2224/48472** (2013.01 - EP US); **H01L 2224/73265** (2013.01 - EP US); **H01L 2224/8319** (2013.01 - EP US); **H01L 2224/83805** (2013.01 - EP US); **H01L 2224/8385** (2013.01 - EP US); **H01L 2224/85201** (2013.01 - EP US); **H01L 2224/85205** (2013.01 - EP US); **H01L 2924/00011** (2013.01 - EP US); **H01L 2924/00013** (2013.01 - EP US); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01006** (2013.01 - EP US); **H01L 2924/0101** (2013.01 - EP US); **H01L 2924/01012** (2013.01 - EP US); **H01L 2924/01013** (2013.01 - EP US); **H01L 2924/01014** (2013.01 - EP US); **H01L 2924/01019** (2013.01 - EP US); **H01L 2924/0102** (2013.01 - EP US); **H01L 2924/01028** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/0103** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP US); **H01L 2924/0104** (2013.01 - EP US); **H01L 2924/01047** (2013.01 - EP US); **H01L 2924/01077** (2013.01 - EP US); **H01L 2924/01078** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H01L 2924/01082** (2013.01 - EP US); **H01L 2924/0132** (2013.01 - EP US); **H01L 2924/01322** (2013.01 - EP US); **H01L 2924/014** (2013.01 - EP US); **H01L 2924/0665** (2013.01 - EP US); **H01L 2924/07802** (2013.01 - EP US); **H01L 2924/09701** (2013.01 - EP US); **H01L 2924/10253** (2013.01 - EP US); **H01L 2924/1301** (2013.01 - EP US); **H01L 2924/14** (2013.01 - EP US); **H01L 2924/15747** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US); **H01L 2924/19041** (2013.01 - EP US); **H01L 2924/19043** (2013.01 - EP US); **H01L 2924/19105** (2013.01 - EP US); **H01L 2924/3025** (2013.01 - EP US)

C-Set (source: EP US)
1. **C08K 3/08 + C08L 83/04**
2. H01L 2924/01322 + H01L 2924/01014 + H01L 2924/01079
3. H01L 2924/0132 + H01L 2924/01014 + H01L 2924/01079
4. H01L 2224/83805 + H01L 2924/00
5. H01L 2224/85205 + H01L 2224/45147 + H01L 2924/00
6. H01L 2224/85205 + H01L 2224/45144 + H01L 2924/00
7. H01L 2224/85205 + H01L 2224/45124 + H01L 2924/00
8. H01L 2224/73265 + H01L 2224/32245 + H01L 2224/48227 + H01L 2924/00
9. H01L 2224/73265 + H01L 2224/32245 + H01L 2224/48247 + H01L 2924/00012
10. H01L 2224/73265 + H01L 2224/32225 + H01L 2224/48227 + H01L 2924/00012
11. H01L 2224/73265 + H01L 2224/32225 + H01L 2224/48247 + H01L 2924/00
12. **C08L 83/04 + C08L 83/00**
13. H01L 2224/29191 + H01L 2924/00014
14. H01L 2924/00013 + H01L 2224/29099
15. H01L 2924/00013 + H01L 2224/29199
16. H01L 2924/00013 + H01L 2224/29299
17. H01L 2924/00013 + H01L 2224/2929
18. H01L 2924/10253 + H01L 2924/00
19. H01L 2924/15747 + H01L 2924/00
20. H01L 2924/1301 + H01L 2924/00
21. H01L 2924/00011 + H01L 2224/83205
22. H01L 2924/181 + H01L 2924/00012
23. H01L 2224/45124 + H01L 2924/00014
24. **C09J 183/04 + C08L 83/00**
25. H01L 2224/45144 + H01L 2924/00014
26. H01L 2224/45147 + H01L 2924/00014
27. H01L 2224/48091 + H01L 2924/00014

28. H01L 2224/29191 + H01L 2924/0715
29. H01L 2924/0665 + H01L 2924/00
30. H01L 2224/29101 + H01L 2924/014 + H01L 2924/00

Citation (search report)

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- [XY] EP 0614946 A1 19940914 - KANEGAFUCHI CHEMICAL IND [JP]
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